

L Number	Hits	Search Text	DB	Time stamp
2	19	((interconnect\$3 or wir\$3) adj substrate) and (substrate with pad\$1) and (test\$4 adj pad\$1) and diode\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/14 09:05
3	27	("4124899" "4327355" "4354228" "4433331" "4455495" "4458297" "4467400" "4479088" "4509008" "4631686" "4649413" "4703436" "4706216" "4717988" "4727268" "4758745" "4786904" "4813017" "4817093" "4821176" "4847732" "4866432" "4873459" "4884122" "4906987" "4949084" "5015885").PN.	USPAT	2002/11/14 08:50
4	28	5371390.URPN.	USPAT	2002/11/14 08:54
5	19	((interconnect\$3 or wir\$3) adj substrate) and (test\$4 adj pad\$1) and diode\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:01
6	28	(support\$3 adj substrate) and (test\$4 adj pad\$1) and diode\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:02
7	1393	257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:49
8	153	257/778.ccls. and ((interconnect\$3 or wir\$3) adj substrate) and pad\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:08
9	13	257/778.ccls. and (test\$3 adj pad\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:15
10	59	(chip\$1 near4 substrate) and (test\$3 adj pad\$1) and diode\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/14 09:24
11	54	("3239719" "4124899" "4183460" "4241307" "4327355" "4354228" "4357703" "4433331" "4441075" "4455495" "4458297" "4467400" "4479088" "4486705" "4509008" "4631686" "4649413" "4703436" "4706216" "4717988" "4727268" "4729124" "4758745" "4786904" "4807183" "4813017" "4817093" "4821176" "4833402" "4840924" "4847732" "4866432" "4870302" "4873459" "4884122" "4894605" "4906987" "4949084" "4956602" "4961053" "4963768" "5015885" "5036473" "5109353" "5144548" "5231588" "5253181" "5255203" "5295082" "5448496" "5452231" "5612891" "5657241" "5661662").PN.	USPAT	2002/11/14 09:16
12	5	5973340.URPN.	USPAT	2002/11/14 09:19

13	183	chip\$1 with diode\$1 with test\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 09:37
14	118	chip\$1 with diode\$1 with ESD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 09:37
15	1963	257/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 09:49
16	556	257/758.ccls. and pad\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 09:55
19	328	((257/211 257/029 257/208).ccls.) and pad\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 11:03
20	1185	(257/208, 029, "211").ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 11:10
-	191	iP with substrat\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 17:47
-	818	257/777.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 09:05
-	11723	(interconnect\$3 or wir\$3) adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 18:07
-	71	((interconnect\$3 or wir\$3) adj substrate) with test\$4 with pad\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 18:22
-	74	((interconnect\$3 or wir\$3) adj substrate) and (substrate with pad\$1) and (test\$4 adj pad\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/14 08:40